

Patent

Customer No.: 31561
 Docket No.: 10073-US-PA
 Application No.: 10/707,609

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Chen et al.
 Application No. : 10/707,609
 Filed : 2003/12/24
 For : FLIP CHIP PACKAGE STRUCTURE
 Art Unit : 2814
 Examiner : Trinh, Vikki II.

RECEIVED
 CENTRAL FAX CENTER

AUG 02 2005

TRANSMITTAL LETTER

002-1-571-273-8300

(Via fax : 1+2+9 pages)

Assistant Commissioner for Patents
 Alexandria, VA 22314.

Dear Sir,

In response to the Office Action dated May 3, 2005(Paper No.: 0405), please find the Response to Office Action, in 9 pages.

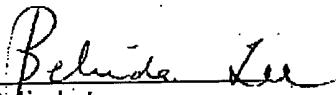
I believe that no fee is incurred. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10073-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
 JIANQ CHYUN Intellectual Property Office

Date : August 2, 2005

By :


 Belinda Lee
 Registration No.: 46,863

Please send future correspondence to:
 7F. -1, No. 100, Roosevelt Rd.,
 Sec. 2, Taipei 100, Taiwan, R.O.C.
 Tel: 886-2-2369 2800 Fax: 886-2-2369 7233 / 886-2-2369 7234
 E-MAIL: BELINDA@JCIPGroup.com.tw; USA@JCIPGroup.com.tw

RECEIVED
 OIPE/IAP

AUG 05 2005